

Tin-Lead

SLOTOLET KB 20

Tin-Lead SLOTOLET KB 20 is a fluoride-free electrolyte for the deposition of semi-bright tin-lead coatings and is applied in high-speed plating lines for plating of IC-leadframes.

Tin-Lead SLOTOLET KB 20 is operated at temperatures between 20 - 40° C with a current density of 10 - 20 A/dm².

Tin-Lead SLOTOLET KB 20 is suitable for plating of zirconium-copper alloys. The additive system prevents the formation of dendrites.

The coatings show excellent solderability, even after accelerated ageing tests. The co-deposition of organics is very low - the carbon content of the deposit is only 0.006%.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given.

We reserve the right to make technical changes as necessary.

In the interests of safety, please pay attention to the R- and S- phrases on the drum label.

The shelf life of the additives is generally 18 months.

The date of production is taken from the first 3 figures of the batch number.

Figure 1 = year; figures 2-3 = month; figures 4-7 = batch number; (UK labels use a 4 digit year code).

For the storage of chemical products only the TRGS 514 and TRGS 515 Regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) are only valid for transportation and must not be applied to storage.

